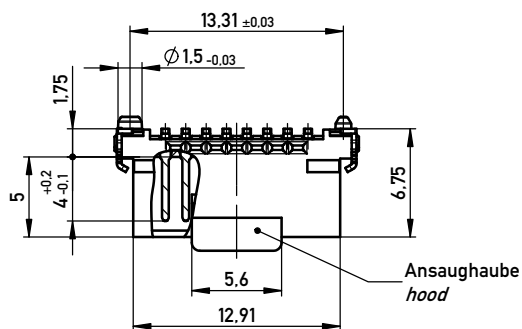
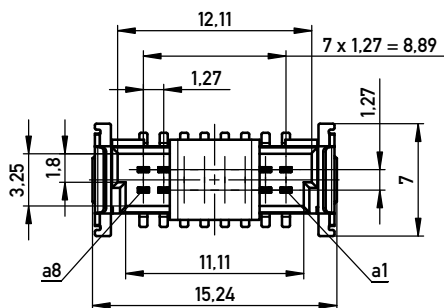
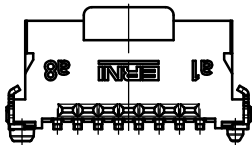
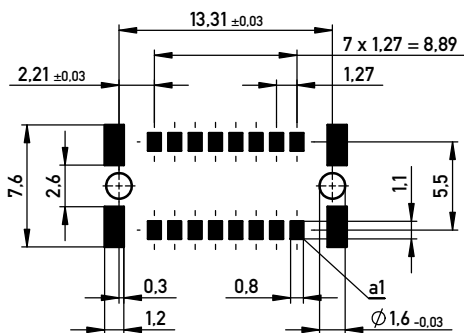


Leiterplatten-Layout Vorschlag für SMT PCB-Layout Proposal for SMT



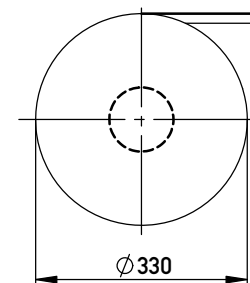
Anforderungsstufe 1
Performance Level 1

Kontaktbereich vergoldet
Mating Area gold plating

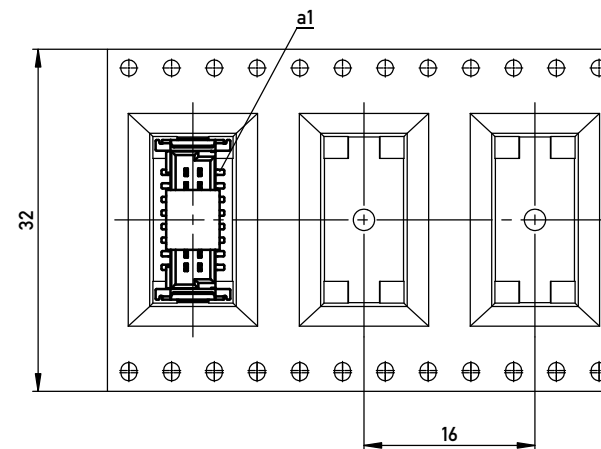
Anschlussbereich verzinkt 4-6 µm
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
Coplanarity Area of Termination ≤ 0,1 mm

Verpackt im Gurt nach DIN IEC 60286-3
Tape on Reel Packaging according to DIN IEC 60286-3
Verpackungseinheit: 280 Stück
Packaging unit: 280 pcs



Abspulrichtung - Reel off Direction



BA 8-13 - 8mm Bauhöhe

type 8-13 - Low Profile

Proprietary notice pursuant to ISO 9001 to be observed.	Information:			Tolerances	 All Dimensions in mm	Scale	3:1	
	All rights reserved. Only for Information. To ensure that this is the latest version of this drawing, please contact one of the ERNI companies before using.			Subject to modification without prior notice. Drawing will not be updated.		Designation Messerl. SMC-Q 16-SMD-BA8-13 <i>Male SMC-Q 16-SMD-type8-13</i>		
e		14.07.2015			www.ERNI.com	254587		I A3
Index		Date				Class	SMCQ	

Copyright by ERNI GmbH
Proprietary notice pursuant to ISO 9006 to be observed.